

Amendments to the Claims:

This listing of claims will replace all prior versions, and listings, of claims in the application:

Listing of claims:

1-16. (canceled)

17. (previously presented) The semiconductor device of claim 18, wherein the chip carrier is selected from a group consisting of a substrate and a leadframe.

18. (currently amended) A semiconductor device comprising:
a semiconductor die having a bottom surface;
a chip carrier;
a die attach material including a component of a tungstate material; and
the semiconductor die attached to the chip carrier with the die attach material, ~~which covers an entire die surface~~ wherein the die attach material covers the entire bottom surface of the semiconductor die.

19. (previously presented) The semiconductor device of claim 18,, further comprising an encapsulant that encapsulates the semiconductor die, the encapsulant including a component of negative-CTE.

20. (previously presented) The semiconductor device of claim 19, wherein the encapsulant includes a tungstate material.

21. (previously presented) The semiconductor device of claim 19, wherein the encapsulant is selected from a group consisting of a mold compound and a glob-top material.

22-24 (cancelled)

25. (previously presented) The semiconductor of claim 19, in which the die attaching material and the encapsulant include a component selected from a group consisting of zirconium tungstate, hafnium tungstate, and a solution of zirconium and hafnium tungstate.